



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-04-29
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
UAE7-BB-TR	HA5W*UAE7BB5	A	959	2020-04-29
	Amount	UoM	Unit type	ST ECOPACK Grade
	350	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00399791	



Package Designator	Size	Nbr of instances	Shape	
QFP	10.00,10.00,1.40	64	gull wing	
Comment	LQFP 64 10x10x1.4 1. MDF valid for CPs: UAE7-BB,UAE7-BB-TR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	3.03	die - leadframe	8676

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration :						Mfr Item Name	HASW*UAE7BB5					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	16.762	mg	supplier	die	Silicon(Si)	7440-21-3		15.619	mg	931810	44664
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.069	mg	4116	197
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.009	mg	538	26
				supplier	metallisation	Copper(Cu)	7440-50-8		0.668	mg	39852	1910
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.002	mg	119	5
				supplier	metallisation	Gold(Au)	7440-57-5		0.024	mg	1432	69
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.044	mg	2625	126
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.005	mg	298	14
				supplier	metallisation	Tungsten(W)	7440-33-7		0.011	mg	656	31
				supplier	metallisation	Vanadium(V)	7440-62-2		0.002	mg	119	6
Leadframe	M-004 Copper and its alloys	99.905	mg	supplier	passivation	Silicon oxide	7631-86-9		0.309	mg	18435	884
				supplier	alloy & coating	Copper(Cu)	7440-50-8		95.882	mg	959732	274184
				supplier	alloy & coating	Nickel(Ni)	7440-02-0		2.990	mg	29928	8550
				supplier	alloy & coating	Magnesium(Mg)	7439-95-4		0.150	mg	1502	429
				supplier	alloy & coating	Silicon(Si)	7440-21-3		0.648	mg	6486	1853
Die attach	M-011 Other inorganic materials	2.455	mg	supplier	alloy & coating	Silver (Ag)	7440-22-4		0.235	mg	2352	672
				supplier	glue	Silver(Ag)	7440-22-4		2.189	mg	891650	6260
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.172	mg	70060	492
				supplier	glue	Bismaleimide resin	proprietary		0.074	mg	30143	212
Bonding wires	M-004 Copper and its alloys	1.030	mg	supplier	glue	Epoxy(cyclohexylethyltrimethoxysilane	3388-04-3		0.020	mg	8147	57
				supplier	wire	Copper(Cu)	7440-50-8		1.030	mg	1000000	2945
Encapsulation	M-011 Other inorganic materials	225.983	mg	supplier	silica	Silica vitreous	60676-86-0		195.249	mg	864000	558333
				supplier	mold compound	Epoxy type resin	proprietary		16.949	mg	75001	48467
				supplier	mold compound	Phenol type resin	proprietary		11.299	mg	49999	32311
				supplier	mold compound	Mercaptopropyl trimethoxysilane	4420-74-0		1.130	mg	5000	3231
				supplier	mold compound	Quartz	14808-60-7		0.678	mg	3000	1939
connections coating	Solder	3.565	mg	supplier	mold compound	Carbon black	1333-86-4		0.678	mg	3000	1939
				supplier	solder alloy	Tin (Sn)	7440-31-5		3.565	mg	1000000	10194